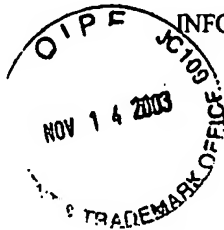




Date: November 12, 2003

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<b>U.S. DEPARTMENT OF COMMERCE</b> <b>PATENT AND TRADEMARK OFFICE</b>  (REV. 05/03)   <b>INFORMATION DISCLOSURE CITATION</b> (Use several sheets if necessary)	<b>ATTY. DOCKET NO.</b> INDUM-110XX	<b>APPLICATION NO.</b> 10/636,105
	<b>APPLICANT:</b> Wushing Yin, et al.	
	<b>FILING DATE</b> 8/7/03	<b>TC ART UNIT</b> 3726

**U.S. PATENT DOCUMENTS**

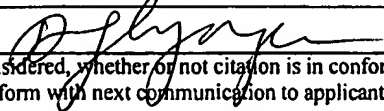
EXAMINER INITIAL	DOCUMENT NUMBER	PUBLICATION/ ISSUE DATE	NAME	CLASS	SUBCLASS	FILING DATE
DN	US2003/0096452	5/22/2003	Yin, et al.	438	108	
	US2003/0096453	5/22/2003	Wang, et al.	438	108	
	US2003/0109080	6/12/2003	Dias	438	108	
	US5,128,746	7/7/1992	Pennisi, et al.	357	72	
	US6,038,136	3/14/2000	Weber	361	783	
	US6,157,086	12/5/2000	Weber	257	788	
DN	US6,168,972	1/2/2001	Wang, et al.	438	108	
	<del>US6,457,828</del>	<del>11/5/2002</del>	<del>Hoang</del>	<del>438</del>	<del>108</del>	
DN	US6,506,681	1/14/2003	Grigg, et al.	438	692	

**FOREIGN PATENT DOCUMENTS**

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
DN	WO 99/56312	11/4/1999	WIPO			X	

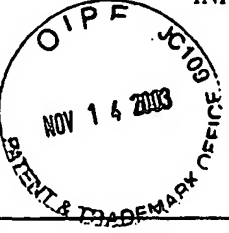
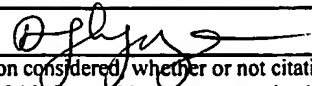
**OTHER DOCUMENTS** (including Author, Title, Date, Pertinent Pages, etc.)

DN	Product Data Sheet; "Epoxy Flip Chip Flux PK-001"; Indium Corporation of America
DN	Product Data Sheet; "Pb-Free Epoxy Flip Chip Flux PK-002"; Indium Corporation of America
DN	Surface Mount Technology; Materials, Processes and Equipment; Carmen Capillo; Unisys Corporation; San Jose, CA

<b>EXAMINER</b> 	<b>DATE CONSIDERED</b> 11/17/03
<b>*EXAMINER:</b> Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

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<b>U.S. DEPARTMENT OF COMMERCE</b> <b>PATENT AND TRADEMARK OFFICE</b>  <b>INFORMATION DISCLOSURE CITATION</b> <i>(Use several sheets if necessary)</i>				ATTY. DOCKET NO. INDUM-110XX		APPLICATION NO. 10/636,105	
				APPLICANT: Wushing Yin, et al.			
				FILING DATE 8/7/2003		TC ART UNIT 3726 5729	
<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER INITIAL	DOCUMENT NUMBER	PUBLICATION/ ISSUE DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	US						
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<b>FOREIGN PATENT DOCUMENTS</b>							
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO	
<b>OTHER DOCUMENTS</b> <i>(including Author, Title, Date, Pertinent Pages, etc.)</i>							
BN	"No Flow Underfill Reliability is Here - Finally?"; Michael A. Previti; Cookson Semiconductor Packaging Materials; Alpharetta, GA						
BN	"The Development of No-Flow Underfill Materials for Flip-Chip Applications"; Dr. C. P. Wong; S. H. Shi; School of Materials Science and Engineering & Packaging Research Center; Georgia Institute of Technology; February 2, 1999						
BN	"No-Flow Underfill Materials for Environment Sensitive Flip-Chip Process; A Dissertation Presented to The Academic Faculty; Zhuqing Zhang; Georgia Institute for Technology; June 2001 Chi Flfor						
BN	"A Novel Approach to Incorporate Silica Filler into No-Flow Underfill"; Zhuqing Zhang, Jicum Lu; C. P. Wong; School of Materials Science and Engineering and Packaging Research Center; Georgia Institute of Technology; Georgia; Pages 1-7						
EXAMINER				DATE CONSIDERED			
				10/17/05			
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